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Notes:

1. Untranslatable words are replaced with asterisks (***)�.
2. Texts in the figures are not translated and shown as is.

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CLAIM + DETAILED DESCRIPTION

[Claim(s)]

[Claim 1]A polish device installing an actuator in which pressurization adjustment is independently possible at two or more places in a mount plate which holds the body to be ground and transmits processing pressure to the body to be ground in a polish device which performs surface polish of the body to be ground using relative rubbing movement between the body to be ground and abrasive cloth.

[Detailed Description of the Invention]**[0001]**

[Industrial Application]This invention relates to a polish device.

[0002]

[Description of the Prior Art]As a conventional polish device, the thing as shown in drawing 5 is known. In drawing 5, 1 is a surface plate and it is the mount head with which the mount plate was equipped with 2 and the upper part of the mount plate 2 was equipped with 3. The surface plate 1 is seen superficially and is carrying out circular rotation board shape.

The upper surface is equipped with the abrasive cloth 4.

[0003]The mount plate 2 is a disk which consists of Ceramics Sub-Division or glass material. As shown in drawing 5, the one or more sheet object 5 to be ground of two or more sheets is being fixed to the undersurface of this mount plate 2. Thus, the field where the body 5 to be ground is being fixed is pressed with the pressurization axis 6 to the abrasive cloth 4 on the surface plate 1, and polish processing is performed by the relative motion of the abrasive cloth 4 and the body 5 to be ground.

[0004]In order to apply uniform pressure to the mount plate 2, with the conventional polish

device with the mount head 3, The method (JP,S63-144953,A) of performing polish processing by pressing the mount plate 2 to the surface plate 1 via the resilient tube of the shape of *** which filled up the inside with fluid, The method (JP,H2-98927,A) of performing polish processing was taken by estranging between the head sections surrounding the mount plate [which fixed the plate-like body 5 to be ground to the undersurface side] 2, and mount plate 2 circumference via a cavity part.

[0005]

[Problem to be solved by the invention]Many following faults exist in the Prior art mentioned above. Namely, since predetermined pressure was given with the pressurization axis 6 etc. as a pressing means at the time of polish, the pressure was transmitted to the mount plate 2 with the conventional polish device as mentioned above and polish processing was performed, With the heat stress modification by the heat distribution generated on the mount plate 2, modification of the mount plate 2 by the heterogeneity of a pressing means, modification of the surface plate 1, the degree accuracy of flat of mount plate 2 the very thing, etc., Uniform pressure could not be given to the body 5 to be ground, but the problem that correspondence was impossible was among polish processings as which the high degree of flat is required.

[0006]This invention solves these above-mentioned problems. The purpose is in offer of the polish device which enables realization of high flat degree polish processing of the body to be ground.

[0007]

[Means for solving problem]To achieve the above objects, the polish device of this invention installed two or more actuators which can adjust pressurization power to the lower part of a mount head independently, and it constituted them so that a mount plate might be pressed via this actuator for pressurization power adjustment.

[0008]

[Function]As shown in drawing 1 - drawing 4, [two or more actuators 7 which can adjust pressurization power independently] Based on the concavo-convex information on the surface after one or more sheet the polish of the body 5 to be ground of two or more sheets fixed to the mount plate 2 undersurface in front of 1 batch, in following batch, it is adjusted independently, respectively so that unevenness of the surface after polish may be negated, and the mount plate 2 is pressed. That is, the degree of high flat is realized by the body 5 to be ground adding high pressure to the press surface of the mount plate 2 of the portion which is a convex, adding low pressure to the portion which is **, grinding a convex part preferentially, and decreasing a vertical interval with a crevice.

[0009]

[Working example]An embodiment is described based on Drawings. Drawing 1 is a figure

showing one embodiment of this invention.

The numerals 1, 2, 3, and 6 are the same surface plate and mount plate as what is used for the conventional polish device, respectively, a mount head, and a pressurization axis.

As usual, the mount plate 2 is laid on the surface plate 1, where the body 5 to be ground is fixed to the undersurface. In the upper part of this mount plate 2, two or more actuators (they are 17 actuators to the radial direction and the direction of the circumference of the mount plate 2) are arranged tidily (drawing 2).

[0010] Although the example shown in drawing 1 has indicated what uses the piezoelectric element 8 for seven copies of pressurization actuators instead, the hydraulic power package 9 can also be used for it like drawing 3, and the ball screw 10 can also be used for it like drawing 4. Anythings are employable if it is a mechanism in which pressurization power can be arbitrarily adjusted independently in short, respectively.

[0011]

[Effect of the Invention] In this invention, as explained above, it is a device with a means to pressurize by the pressurization actuator which installed the mount plate in the plurality which can be adjusted independent, and is a device which can adjust the thrust from a mount plate actively.

Therefore, it is not influenced by disturbance but polish processing which can obtain the high degree of flat can be realized.

[Translation done.]